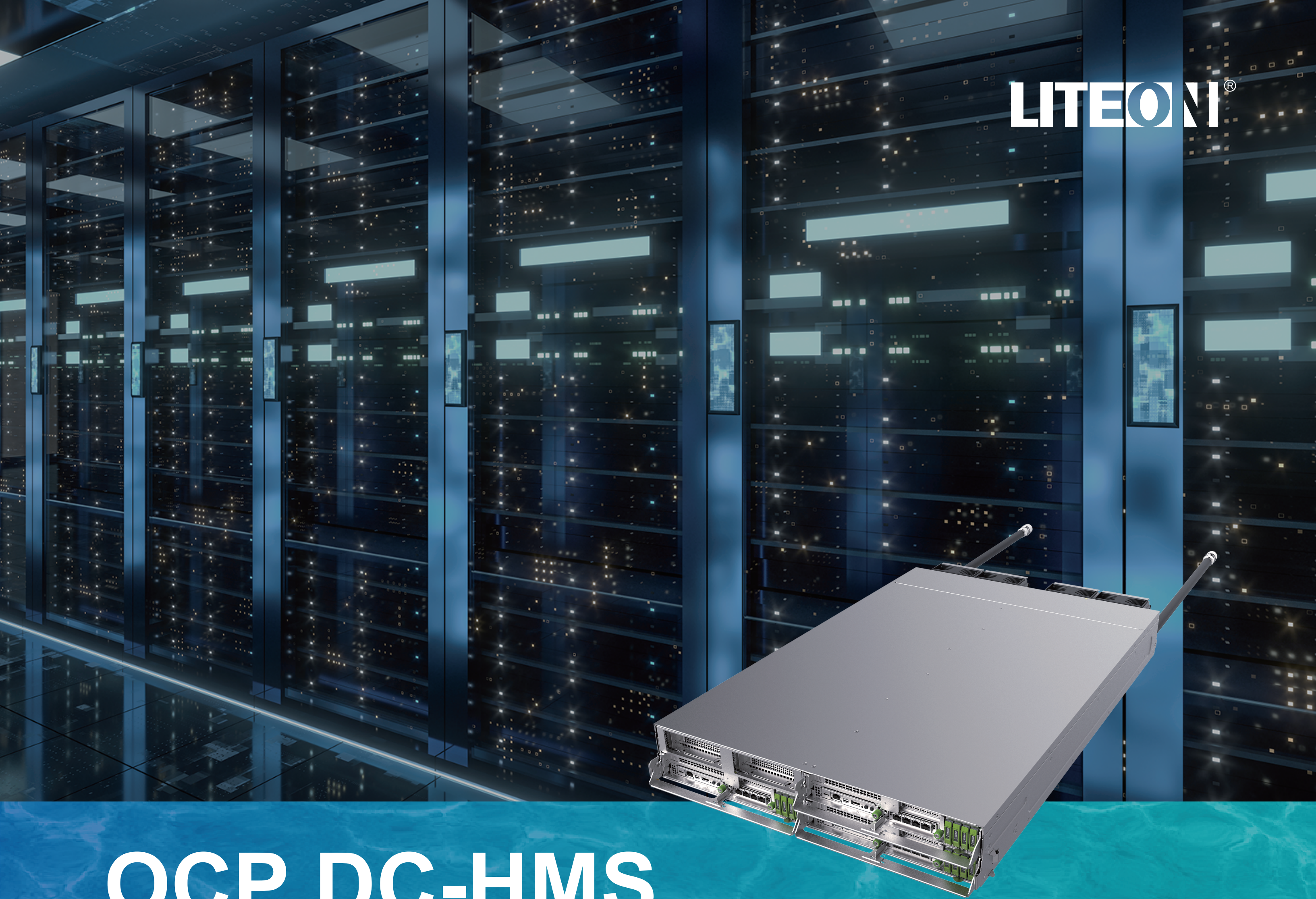


LITEON®

OCP DC-HMS
Multi-Node Server

Key Features

OCP ORV3 Compliance
2OU rackmountable
Support 2 Nodes or 4 Nodes
Support Busbar Power Solution

DC-MHS Chassis Design
Support M-DNO Type 2 & Type 3 HPM
OCP DC-SCM 2.0 Secure Control Module
OCP 3.0 NIC Network Interface

Future Flexibility
Support DLC Thermal Solution

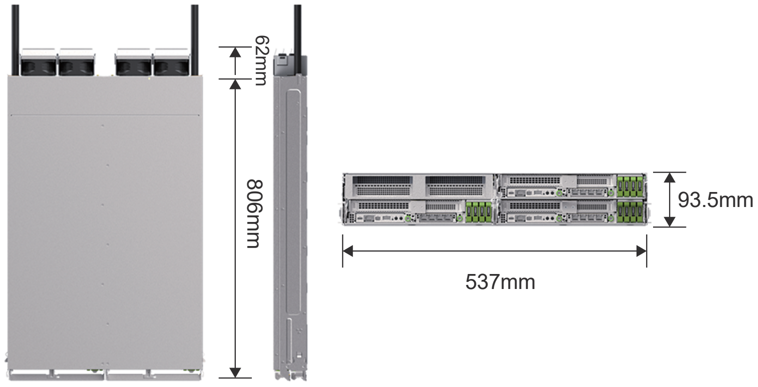
Applications

- AI
- HPC (High Performance Computing)
- Data Analytics
- Deep Learning Training
- Deep Learning Inference

Specification

Application	Suit in ORV3 open rack server, be applied to computing node & GPU node.
CPU	Single or dual sockets per node for Intel/AMD/ARM processors
Memory	Up to 32 DDR5 DIMMs (Each CPU supports up to 16*DIMMs) per Node
Storage	4 x E1.s SSD (EDSFF) per node
Network	1 x OCP 3.0 NIC Slot
Management	1 x OCP DC-SCM 2.0
Expansion Slots	1 x FH/HL PCIE GEN5 x16 slot per node / 1 x LP PCIE GEN5 x16 slot per node / 2 x GW GPU GEN5 x16 slot for 2N model
System FAN	4 x 9238 Fan
Optional module	DLC (Direct Liquid Cooling) module with blind-mate quick connector for node installation
Dimensions (W x D x H mm)	537.0 x 93.5 x 806 mm
Form Factor	2OU rackmount
Operation Temp.	-5°C – 45°C
Storage Temp.	-40°C – 70°C
Humidity	10% – 90% relative (non-condensing)

Dimension Details



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